SN54174, SN54175, SN54LS174, SN54LS175, SN54S174, SN54S175, SN74174, SN74LS174, SN74LS175, SN74S174, SN74S175, HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

SDLS068

DECEMBER 1972-REVISED MARCH 1988

'174, 'LS174, 'S174 . . . HEX D-TYPE FLIP-FLOPS '175, 'LS175, 'S175 QUADRUPLE D-TYPE FLIP-FLOPS

- '174, 'LS174, 'S174 Contain Six Flip-Flops with Single-Rail Outputs
- '175, 'LS175, 'S175 Contain Four Flip-Flops with Double-Rail Outputs
- Three Performance Ranges Offered: See Table Lower Right
- Buffered Clock and Direct Clear Inputs
- Individual Data Input to Each Flip-Flop
- Applications include:

 Buffer/Storage Registers

 Shift Registers
 Pattern Generators

description

These monolithic, positive-edge-triggered flip-flops utilize TTL circuitry to implement D-type flip-flop logic. All have a direct clear input, and the '175, 'LS175, and 'S175 feature complementary outputs from each flip-flop:

Information at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output.

These circuits are fully compatible for use with most TTL circuits.

FUNCTION TABLE

	IMPUTS			PUTS
CLEAR	D	Q	ō٢	
L	×	X	L,	Н
н	†	н	н	L
н	1	L	L	Н
н	L	x	σo	ā _o

H = high level (steady state)

L = low level (steady state)

X = irrelevant

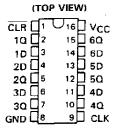
1 - transition from low to high level

 \mathbf{Q}_0 = the level of \mathbf{Q} before the indicated steady-state input conditions were established.

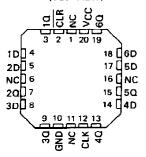
1 = '175, 'LS175, and 'S175 only

	TYPICAL	TYPICAL
TYPES	MAXIMUM	POWER
ITPES	CLOCK	DISSIPATION
	FREQUENCY	PER FLIP-FLOP
174, 175	35 MHz	38 mW
'LS174, 'LS175	40 MHz	14 mW
'S174. 'S175	110 MHz	75 mW

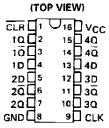
SN54174, SN54LS174, SN54S174.... J OR W PACKAGE SN74174.... N PACKAGE SN74LS174, SN74S174.... D OR N PACKAGE



SN54LS174, SN54S174 . . . FK PACKAGE (TOP VIEW)

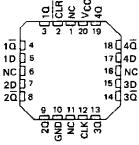


SN54175, SN54LS175, SN54S175 . . . J OR W PACKAGE SN74175 . . . N PACKAGE SN74LS175, SN74S175 . . . D OR N PACKAGE



SN54LS175, SN54S175 . . . FK PACKAGE

(TOP VIEW)



NC - No internal connection

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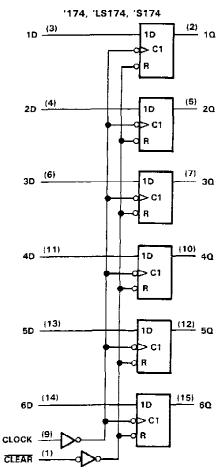


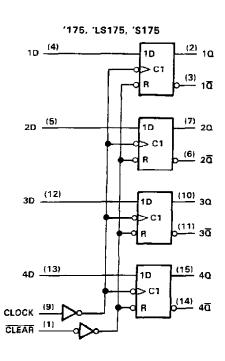
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SN54174, SN54175, SN54LS174, SN54LS175, SN54S174, SN54S175, SN74174, SN74LS174, SN74LS175, SN74LS175, SN74LS175, SN74LS175, SN74S175, SN

logic symbols † 174 1175 CLR (1) ~ CLR (9) (9) CLK CLK C1 **(2)** (2) 10 1D (4) 10 10 1D (5) 1D (4) (3) 2D 2Q ıδ (7) 20 (6) (7)3D 30 2D (5) (6) 2Q (11)(10) 4D 40 (12) 50 (10) 3Q (13) 3D (12) 5D (11) 30 (15) (14) 6Q 6D (15) 4Q (13) 4D (14) 40

logic diagrams (positive logic)





Pin numbers shown are for D, J, N, and W packages.



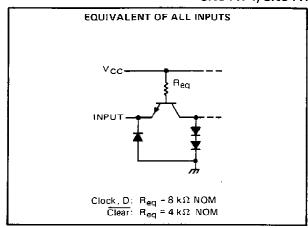
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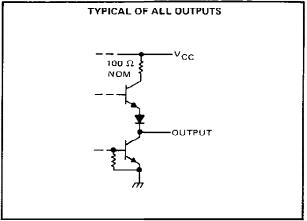
¹These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

SN54174, SN54175, SN54LS174, SN54LS175, SN54S174, SN54S175, SN74174, SN74LS174, SN74LS175, SN74S174, SN74LS175, SN74LS175, SN74S174, SN54LS175, SN54LS175, SN54S174, SN54LS175, SN54LS174, SN54LS175, SN54LS175, SN54S174, SN54LS175, SN54LS175, SN54LS175, SN54LS175, SN54LS175, SN54S174, SN54LS175, SN74LS175, SN54LS175, SN54LS175,

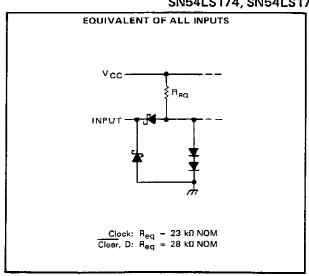
schematics of inputs and outputs

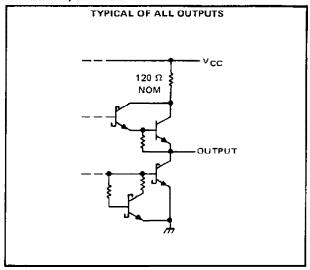
SN54174, SN54175, SN74174, SN74175



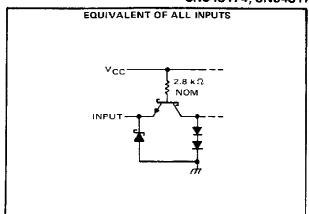


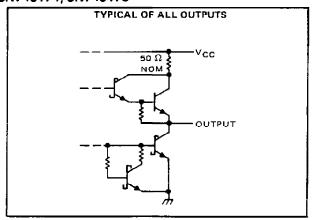
SN54LS174, SN54LS175, SN74LS174, SN74LS175





SN54S174, SN54S175, SN74S174, SN74S175







SN54174, SN54175, SN74174, SN74175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

recommended operating conditions

		SN54174, SN54175			SN74	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	ONLL
Supply voltage, VCC		4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH	-			-800			-800	μА
Low-level output current, IOL		1		16			16	mA
Clock frequency, fclock		0		25	0		25	MHz
Width of clock or clear pulse, t _W		20			20			ns
Control of the contro	Data input	20			20			ns
Setup time, t _{su}	Clear inactive-state	25	•		20 n	ns		
Data hold time, th		5			5			ns
Operating free-air temperature, TA	· · · · · · · · · · · · · · · · · · ·	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	MIN	TYP‡	MAX	UNIT
ViH	High-level input voltage		2			V
VIL	Low-level input voltage				0.8	V
Vik	Input clamp voltage	V _{CC} = MIN, I ₁ = -12 mA			-1.5	V
νон	High-level output voltage	$V_{CC} = MIN$, $V_{IH} = 2 V$, $V_{IL} = 0.8 V$, $I_{OH} = -800 \mu A$	2.4	3.4		٧
VOL	Low-level output voltage	$V_{CC} = MIN$, $V_{1H} = 2 V$, $V_{1L} = 0.8 V$, $I_{OL} = 16 \text{ mA}$		0.2	0.4	٧
11	Input current at maximum input voltage	V _{CC} = MAX, V _I = 5.5 V			1	mΑ
ΊΗ	High-level input current	V _{CC} = MAX, V _I = 2.4 V			40	μΑ
IJĽ	Low-level input current	V _{CC} = MAX, V _I = 0.4 V			-1.6	mA
		SN54'	-20		-57	
los	Short-circuit output current§	V _{CC} = MAX	-18		-57	mΑ
		V - 110 V See Note 2 '174		45	65	
ICC	Supply current	VCC = MAX, See Note 2 175		30	45	mΑ

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type.

switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax Maximum clock frequency		25	35		MHz
Propagation delay time, low-to-high-level output from clear tPLH (SN54175, SN74175 only)	C _L = 15 pF,		16	25	ns
tpHL Propagation delay time, high-to-low-level output from clear	R _L = 400 Ω, See Note 3		23	35	ns
Propagation delay time, low-to-high-level output from clock			20	30	пѕ
tpHL Propagation delay time, high-to-low-level output from clock			24	35	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



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 $^{^\}ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25°C.

^{\$} Not more than one output should be shorted at a time.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, I_{CC} is measured after a momentary ground, then 4.5 V, is applied to clock.

SN54LS174, SN54LS175, SN74LS174, SN74LS175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

recommended operating conditions

		SN54LS174			SN74LS174			
		SI	N54LS1	75	SN74LS175			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, VCC		4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH				-400			-400	μА
Low-level output current, IQL				4			8	mА
Clock frequency, felock		0		30	0		30	MHz
Width of clock or clear pulse, tw		20			20			ns
Control	Data input	20			20			ns
Setup time, t _{SU}	Clear inactive-state	25			25		30	ns
Data hold time, th		5			5			ns
Operating free-air temperature, TA		-55		125	0		70	3°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST	TEST CONDITIONS [†]			SN54LS174 SN54LS175		SN74LS174 SN74LS175			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
v_{IH}	High-level input voltage				2			2	-		٧
VIL	Low-level input voltage						0.7			0.8	V
VIK	Input clamp voltage	V _{CC} = MIN,	I _I = -18 mA				-1.5			-1.5	٧
Voн	High-level output voltage	V _{CC} = MIN, V _{IL} = V _{(L} max,		4	2.5	3.5		2.7	3.5		٧
VOL	Low-level output voltage	VCC = MIN,	•••	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	>
- OL	LOW ICEC despot voltage	Vir = Vir wax		I _{OL} = 8 mA					0.35	0.5	
Ц	Input current at maximum input voltage	VCC = MAX.	V _I = 7 V				0.1			0.1	mA
ЧН	High-level input current	V _{CC} = MAX,	V ₁ = 2.7 V				20			20	μА
1 ₁ L	Low-level input current	V _{CC} = MAX,	V ₁ = 0.4 V				-0.4	-		-0.4	mΑ
los	Short-circuit output current §	V _{CC} = MAX			-20		-100	-20		-100	mΑ
loc	Supply current	VCC = MAX,	See Note 2	'LS174		16	26		16	26	A
Icc	Supply current VCC = MAX, See No	Dec NOTE Z	'L\$175		11	18		11	18	mΑ	

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CONDITIONS	'LS174			'LS175			
PANAMETER	LEST COMPLITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
f _{max} Maximum clock frequency		30	40		30	40		MHz
TPLH Propagation delay time, low-to-high-level output from clear	C _L = 15 pF.					20	30	ns
tpHL Propagation delay time, high-to-low-level output from clear	$R_L = 2 k\Omega$,		23	35		20	30	ns
tpLH Propagation delay time, low-to-high-level output from clock	See Note 3		20	30		13	25	ns
tpHL Propagation delay time, high-to-low-level output from clock	1		21	30		16	25	пs

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



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 $[\]frac{4}{7}$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 \text{ C}$.

Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, I_{CC} is measured after a momentary ground, then 4.5 V, is applied to clock.

SN54S174, SN54S175, SN74S174, SN74S175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

 Supply voltage, V_{CC} (see Note 1)
 7 V

 Input voltage
 5.5 V

 Operating free-air temperature range:
 SN54S174, SN54S175 Circuits
 -55°C to 125°C

 Storage temperature range
 SN74S174, SN74S175 Circuits
 -65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54S174, SN54S175			SN745			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC		4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH				-1			1	mΑ
Low-level output current, IOL				20			20	mA
Clock frequency, fclock		0	***	75	0		75	MHz
Di tan middle a	Clack	7			7			
Pulse width, t _w	Clear	10			10			пs
	Data input	5			5	•		
Setup time, t _{su}	Clear inactive-state	5			5			ns
Data hold time, t _h		3			3		_	ns
Operating free-air temperature, TA		-55		125	0		70	°Ç

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS [†]			TYP‡	MAX	UNIT
ViH	High-level input voltage			2			V
VIL	Low-level input voltage					8.0	٧
Vik	Input clamp voltage	VCC = MIN, II = -18 mA				-1.2	٧
	14: 1 1 4 4 4 10 4	V _{CC} = MIN, V _{1H} = 2 V,	SN54S'	2.5	3.4	-	
VOH	High-level output voltage	V _{IL} = 0.8 V, I _{OH} = -1 mA	SN745'	2.7	3.4		\ \
	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V,				0.5	v
VOL		V ₁ L = 0.8 V, I _O L = 20 mA		1		0.5	'
l _l	Input current at maximum input voltage	V _{CC} = MAX, V ₁ = 5.5 V				1	mΑ
чн	High-level input current	V _{CC} = MAX, V ₁ = 2.7 V				50	μΔ
1 ₁ L	Low-level input current	V _{CC} = MAX, V ₁ = 0.5 V			.	-2	mΑ
los	Short-circuit output current§	V _{CC} - MAX		-40		-100	mA
	•	M MAY O N . O	174		90	144	
1CC	Supply current	V _{CC} = MAX, See Note 2	1175		60	96	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax	Maximum clock frequency		75	110		MHz
tpLH	Propagation delay time, low-to-high-level Q output from clear (SN54S175, SN74S175 only)	C _L = 15 pF,		10	15	ns
^[PHL]	Propagation delay time, high-to-low-level Q output from clear	R _L = 280 Ω, See Note 3		13	22	ns
tPLH	Propagation delay time, low-to-high-level output from clock	Dee More 2		8	12	ns
[‡] PHL	Propagation time, high-to-low-level output from clock			11.5	17	пs

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



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 $[\]ddagger$ All typical values are at V_{CC} = 5 V, \mp_A = 25°C.

Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, I_{CC} is measured after a momentary ground, than 4.5 V, is applied to clock.

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